ASSOCIATION CONNEC	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute														
Supplier Info	rmation															
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*				
nsemi													2024-05-03			
Contact Name			Title - Contac	Title - Contact			Phone - Contact*					Email - Contact*				
Product-Env-Ste	ewards	Product Enviro Compliance			]	NA				Produ	Product-Env-Stewards@onsemi.com					
uthorized Repr	esentative*	Title - Representative			F	Phone - Representative*				Email -	Email - Representative*					
Product-Env-Ste	ewards	Product Enviro Compliance			1	NA				Produ	Product-Env-Stewards@onsemi.com					
Reque	ester Item Number			em Number Mfr Item Name 58061SNAIT1G Ideal Diode NMOS Driver			Effective Date	Version	Version Manufacturing Site		lite	Weight*		UOM	Unit Type	
							2024-05-03 M		MY1		13.66 mg		Each			
/ // // // // // // // // // // // // //	ng Proccess Informatio	on					,		1						,	
Termi	ninal Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	ΓD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Tempera		iture	ure Number of Reflow Cycles		eles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		Au) (no	CU Alloy 1		1		260	С		30	seco		3			
Comments					•		•			•	•	•				
vel 1 - maximu	m time at peak temperature	during so	ldering is 10-3	0 seconds												
	ation regarding material co															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.44	mg	Supplier	Silicon (Si)	7440-21-3		0.44	mg
Die Attach Epoxy	0.06	mg		Epoxy resin	proprietary data		0.039	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.021	mg
Lead Frame	5.44	mg	Supplier	Silver (Ag)	7440-22-4		0.0664	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0065	mg
			Supplier	Iron (Fe)	7439-89-6		0.1278	mg
			Supplier	Copper (Cu)	7440-50-8		5.2376	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0016	mg
Mold Compound-Black	7.33	mg		Epoxy resin	proprietary data		0.5498	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1832	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.5498	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0366	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.0106	mg
Plating	0.35	mg	Supplier	Palladium (Pd)	7440-05-3		0.0088	mg
			В	Nickel (Ni)	7440-02-0		0.3325	mg
			Supplier	Gold (Au)	7440-57-5		0.0088	mg
Wire Bond - Cu	0.04	mg	Supplier	Palladium (Pd)	7440-05-3		0.0007	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0392	mg